

IoT SuperServer SYS-220HE-FTNR-NEBS

X12 DP 2U Short-depth front I/O System with 6 NVMe/SATA bays and redundant AC PSU (NEBS certificated)



More details here

Key Applications

Telecom Micro Data Center, AI Inference and Machine Learning, Cloud Computing, Network Function Virtualization (NFV), 5G Networking,

Key Features

- Dual Socket P+ (LGA-4189) 3rd Gen Intel® Xeon® Scalable Processors;
- 32 DIMM Slots; Up to 8TB DRAM; Up to 8TB Intel® Optane™ Persistent Memory (up to 12TB with DRAM); 3200/2933/2666 ECC DDR4 LRDIMM; RDIMM; Intel® Optane™ Persistent Memory 200 series;
- 3 PCIe 4.0 x16 slots with GPU/Accelerator support (Default); 1 PCIe 4.0 x16 expansion slots (Optional);
- Flexible networking options with 2 AIOM networking slots (OCP NIC 3.0 compatible);
- Up to 6x 2.5" hot-swap drive bays with options to support NVMe/SATA drives;
- 6 heavy duty hot-swap fans with optimal fan speed control Front I/O, tool-less design;
- Redundant 2000W redundant AC power supplies;



Form Factor

2U Rackmount
Enclosure: 436.88 x 88.9 x 574mm (17.2" x 3.5" x 22.6")
Package: 598 x 247 x 938mm (23.5" x 9.7" x 36.9")

Processor

Dual Socket P+ (LGA-4189)
3rd Gen Intel® Xeon® Scalable processors

GPU

Up to 4 double-width GPUs

System Memory

Slot Count: 32 DIMM slots
Max Memory (2DPC): Up to 8TB 3200MT/s ECC DDR4 RDIMM/LRDIMM

Drive Bays Configuration

Default: Total 6 bays
• 6 front hot-swap 2.5" NVMe/SAS/SATA drive bays
M.2: 2 M.2 NVMe/SATA slots (M-key 2280/22110)

Expansion Slots

Default
• 3 PCIe 4.0 x16 FHFL slots
• 1 PCIe 4.0 x16 FHHL slot
Option A
• 6 PCIe 4.0 x8 (in x16) FHFL slots
• 2 PCIe 4.0 x8 (in x16) FHHL slots

On-Board Devices

Network Connectivity: 2 RJ45 1GbE with Intel® I350-AM2 (optional)
4 SFP 1GbE with Intel® I350-AM4 (optional)
2 RJ45 10GBASE-T with Intel® X550-AT2 (optional)
2 SFP+ 10GbE with Intel® X710-BM2 (optional)
4 SFP+ 10GbE with Intel® XL710-BM1 (optional)
4 SFP+ 10GbE with Intel® X710-TM4 (optional)
2 SFP28 25GbE with Broadcom® BCM57414 (optional)
4 SFP28 25GbE (optional)
2 QSFP28 100GbE with Broadcom® BCM57508 (optional)
4 RJ45 1GbE with Intel® I350-AM4 (optional)
BMC: ASPEED AST2600 BMC

Input / Output

LAN: 1 RJ45 1 GbE Dedicated BMC LAN port
USB: 2 USB 2.0 ports(front)
Video: 1 VGA port

System Cooling	Fans: Up to 6 Counter-rotating, Hot-swappable 60x60x56mm Fan(s) Air Shroud: 4 Air Shrouds
Power Supply	1x 2000W Redundant Titanium (certification pending) Level (96%) power supply
Management	SuperCloud Composer® (SCC); Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); Supermicro SuperDoctor® 5 (SD5); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory Fan: Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Weight: Gross Weight: 47.4 lbs (21.5 kg) Net Weight: 34.4 lbs (15.6 kg) Available Color: Silver
Operating Environment	Operating Temperature: 5°C to 35°C (41°F to 95°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X12DHM-6
Chassis	CSE-HE211-R000NFP
